

Title (en)  
DAMPING BODY FOR PACKAGING AND PACKAGE BODY

Title (de)  
DÄMPFUNGSKÖRPER FÜR VERPACKUNG UND VERPACKUNGSKÖRPER

Title (fr)  
CORPS D'AMORTISSEMENT POUR EMBALLAGE ET CORPS D'EMBALLAGE

Publication  
**EP 2123572 A4 20111207 (EN)**

Application  
**EP 07768307 A 20070706**

Priority

- JP 2007063575 W 20070706
- JP 2007027210 A 20070206

Abstract (en)  
[origin: EP2123572A1] A damping body for packaging and a package body which can efficiently absorb impacts at the time of falling are provided. Between an abutment 25 adapted to abut against a precision substrate storage container 3 upon packaging and an outer peripheral wall 22 rising from an outer peripheral edge of a bottom part 21 having the abutment 25, an outer peripheral bottom 26 is formed at a position distanced more from the abutment 25 than is the precision substrate storage container 3, and a stepped part 27 is formed between the outer peripheral bottom 26 and the abutment 25. Consequently, in the event of an impact from the outside, the stepped part 27 collapses, so that the abutment 25 favorably moves with respect to the outer peripheral bottom 26 and thus can efficiently absorb the impact. This can prevent large impacts from instantaneously being exerted on the precision substrate storage container 3 and efficiently damp drop impacts.

IPC 8 full level  
**B65D 81/113** (2006.01); **B65D 81/133** (2006.01); **B65D 85/86** (2006.01); **H01L 21/673** (2006.01)

CPC (source: EP KR)  
**B65D 5/5088** (2013.01 - EP); **B65D 81/113** (2013.01 - KR); **B65D 85/00** (2013.01 - KR); **B65D 85/48** (2013.01 - KR); **H01L 21/673** (2013.01 - KR); **H01L 21/67369** (2013.01 - EP); **H01L 21/67386** (2013.01 - EP)

Citation (search report)

- [Y] JP 2001019050 A 20010123 - SONY CORP
- [Y] US 2006019411 A1 20060126 - UEDA SHIGEAKI [JP], et al
- [Y] JP 2002160769 A 20020604 - SHINETSU POLYMER CO
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Citation (examination)

- EP 1950151 A1 20080730 - SHINETSU POLYMER CO [JP]
- JP 2004168324 A 20040617 - KANEGAFUCHI CHEMICAL IND

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DOCDB simple family (publication)  
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